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Costello et al.(54) **SOCKET ALIGNMENT AND RETENTION SYSTEM***H05K 2201/10189* (2013.01); *H05K 2201/10318* (2013.01); *H05K 2201/10325* (2013.01)(71) Applicant: **TE Connectivity Services GmbH**,
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An electronic module includes a module substrate has an upper surface and a lower surface. The module substrate has a package pad array having package contact pads at the upper surface. The module substrate has a socket pad array having socket contact pads at the upper surface. The module substrate has guide pin locating pads associated with the socket pad array. The electronic module has an electronic package coupled to the package contact pads at the package pad array. The electronic module has guide pins surface mounted to the guide pin locating pads. The electronic module has a socket assembly coupled to the module substrate. The socket assembly has a socket housing holding socket contacts. The socket contacts are coupled to the socket contact pads at the socket pad array. The socket frame including pockets receiving the guide pins to locate the socket assembly relative to the module substrate.

